

Docket No.: YU50-131

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that the information given below is true, that I believe that I am the original, first and sole inventor if only one name is listed below, or a joint inventor if plural inventors are named below, of the invention entitled Formation of Electroplate Solder on An Organic Circuit, Board which is described and disclosed in: for Flip Chip Joints and Board to Board Solder Joints

- (X) the attached specification, or
() the specification in Application Serial No. _____,
filed _____, or
() as amended on _____,

and for which a patent is sought, and that my residence, post office address and citizenship are as stated below next to my name.

I, acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by the amendment referred to above (if any).

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of the following foreign application listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application:

Priority Claimed

Country	Appl. No.	Filing Date
TAIWAN	90118363	July 27, 2001

Yes / No

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application are not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

Application Serial No. _____

Filing Date _____

Status _____

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As the named inventor, I hereby appoint the following attorney(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

RAYMOND SUN, Reg. No. 35, 699

Send all correspondence to:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As the named inventor, I hereby appoint the following attorney(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

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